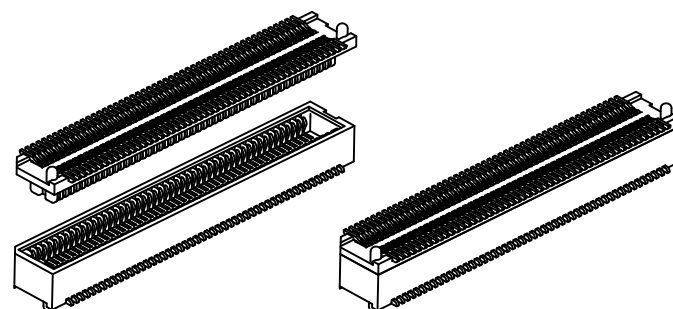
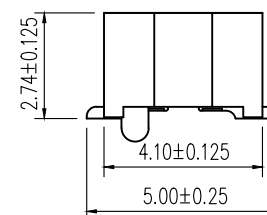
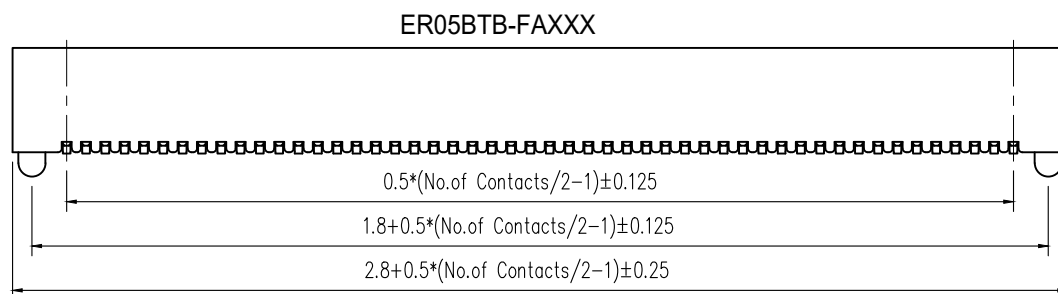
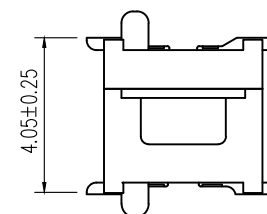
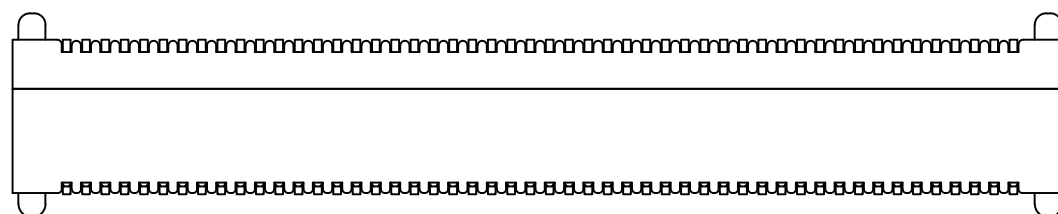
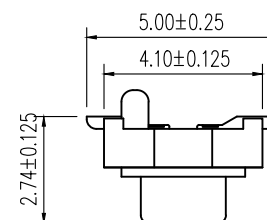
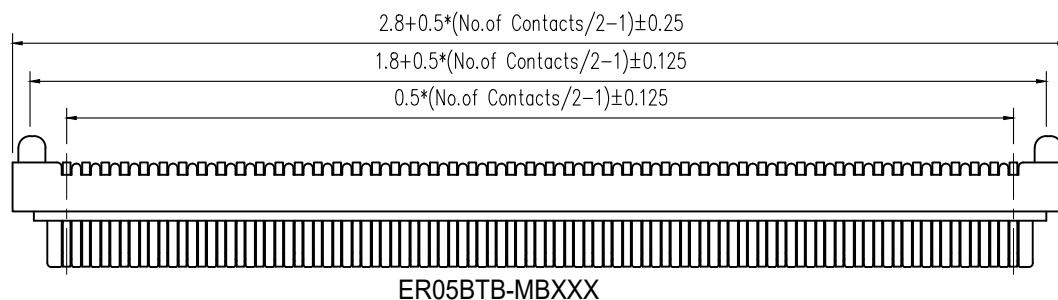


REV.	DESCRIPTION	DATE



NOTE

A. Material:

1. Housing : Nylon-9T Halogen Free, UL94V-0, Black
2. Contact : Copper Alloy

B.Plating: Gold plating

C.Temperature: -55° to 125°

D.Electrical:

1. Voltage : 50V.
2. Current : 0.5A.
3. Contact Resistance : 40m Ω max.
4. Dielectric Withstanding Voltage : 500V AC / 1 min.
5. Insulation Resistance : 100M Ω min.

E.Available Pins : 20~100 Contacts

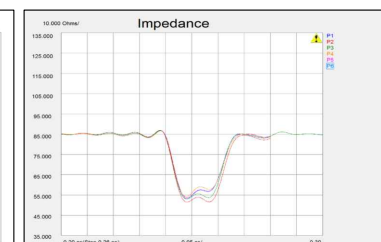
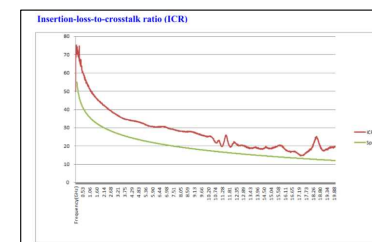
F.Signal integrity features

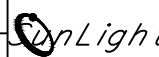
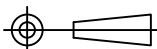
1.Insertion Loss-to-Crosstalk-Ratio (ICR)

The insertion loss-to-crosstalk ratio (ICR) with 5-aggressor differential FEXT meets the IEEE802.3ap specification for 10Gbps with plenty of margins.

2.Differential Impedance

The differential impedance is 85Ω at 35 ps rise time.
(20% to 80%)



TOLERANCE .X ±0.30 .XX ±0.20 .XXX±0.10	DRAWER <i>Chin Chun Liu</i>	 日亮電子科技有限公司 <i>Sun-Light Electronic Technologies Inc.</i>	
	CHECK <i>Haw Feng Liu</i>		
	DESIGNED <i>Chin Chun Liu</i>	NAME 10+Gbps 0.5mm (0.0197") Pitch Board To Board Connectors Male+Female Stacking Hight=4.0mm	
 UNITS : mm	APPROVAL <i>Haw Feng Liu</i>	PART NO. ER05BTB-H40	DRAW NO. ER05BTB-H40
	DATE 7/17/2018	SHEET 1 OF 3	REV. A
SCALE 5 : 1	SIZE A4		

REV.	DESCRIPTION	DATE

NOTE

A. Material:

1. Housing : Nylon-9T Halogen Free, UL94V-0, Black
2. Contact : Copper Alloy
3. Cap : Nylon-9T Halogen Free, UL94V-0, Black

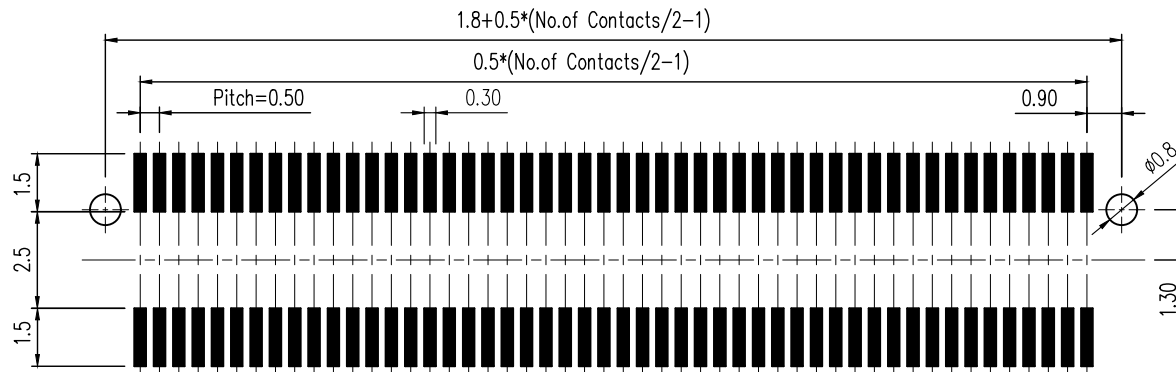
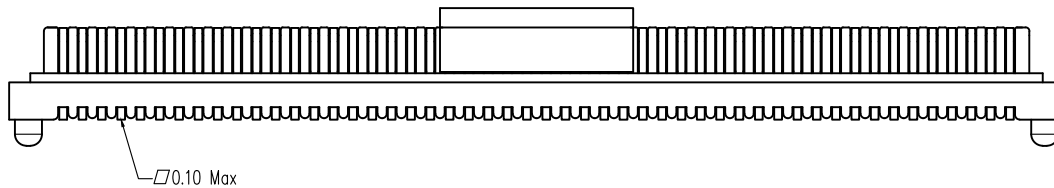
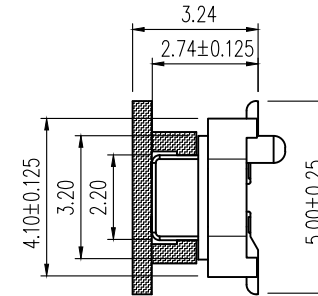
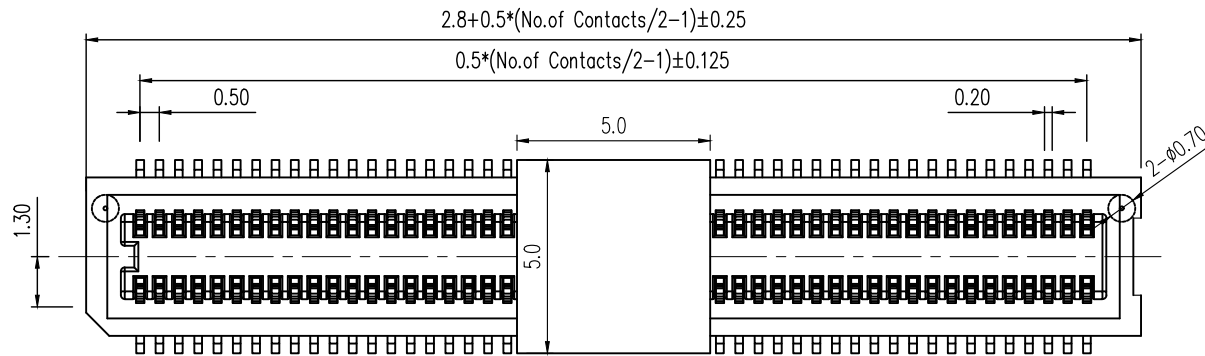
B.Plating: Gold plating

C.Temperature: -55° to 125°

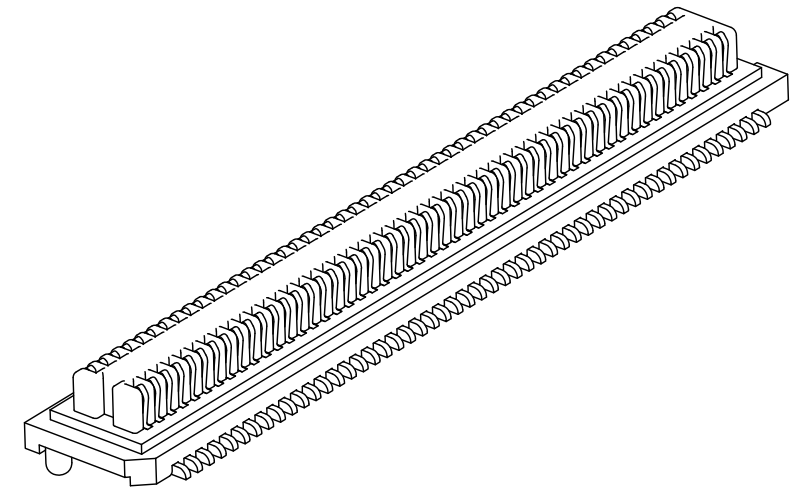
D.Electrical:

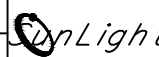
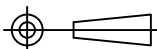
1. Voltage : 50V.
2. Current : 0.5A.
3. Contact Resistance : 40m Ω max.
4. Dielectric Withstanding Voltage : 500V AC / 1 min.
5. Insulation Resistance : 100M Ω min.

E.Available Pins : 20~100 Contacts

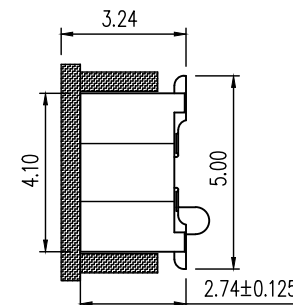
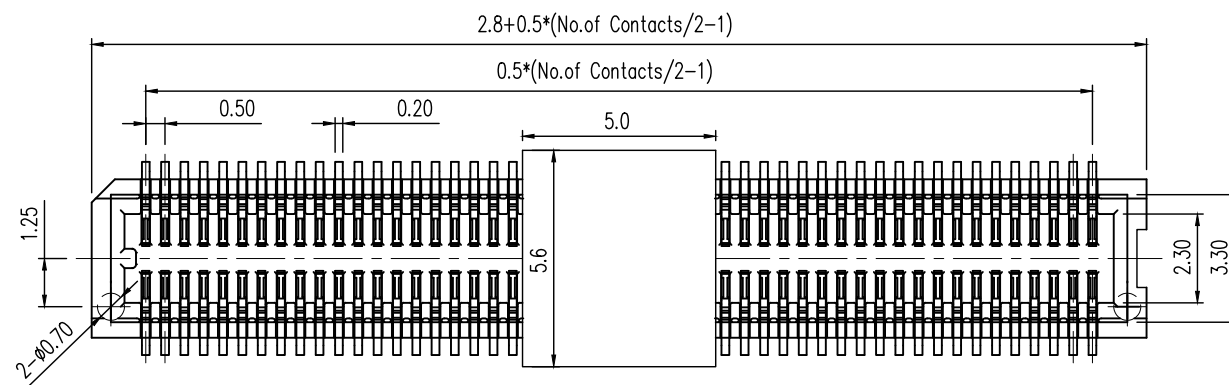


PCB Layout For
Surface Mounting



TOLERANCE .X ±0.30 .XX ±0.20 .XXX±0.10	DRAWER <i>Haw Feng Liu</i>	 日亮電子科技有限公司 Sun-Light Electronic Technologies Inc.	
	CHECK <i>Haw Feng Liu</i>		
	DESIGNED <i>Chin Chun Liu</i>	NAME 10+Gbps 0.50mm (0.0197") Pitch Board To Board Male connectors B-type H=2.74mm	
	APPROVAL <i>Haw Feng Liu</i>		
 UNITS : mm	DATE 7/17/2018	PART NO. ER05BTB-MBXXX	DRAW NO. ER05BTB-MB
	SCALE 5 : 1	SHEET 2 OF 3	REV. A

REV.	DESCRIPTION	DATE



NOTE

A. Material:

1. Housing : Nylon-9T Halogen Free, UL94V-0, Black
2. Contact : Copper Alloy
- 3.Cap : Nylon-9T Halogen Free, UL94V-0, Black

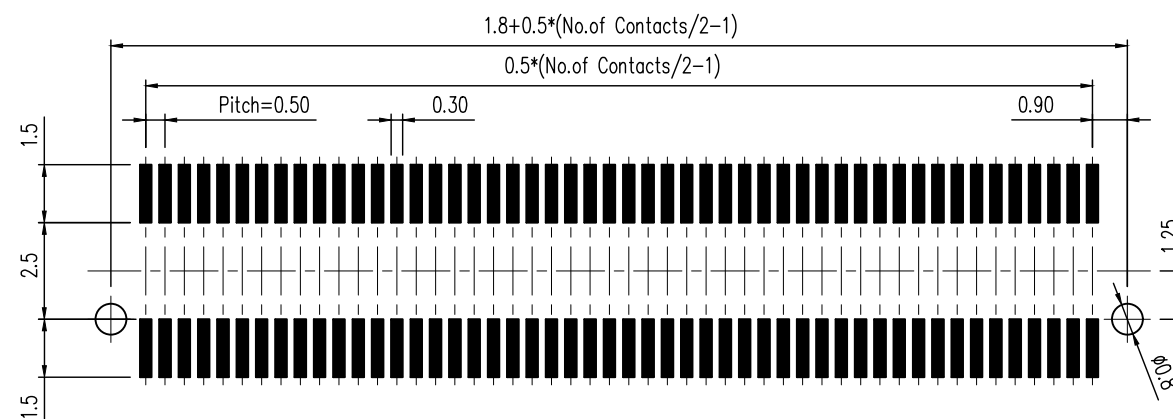
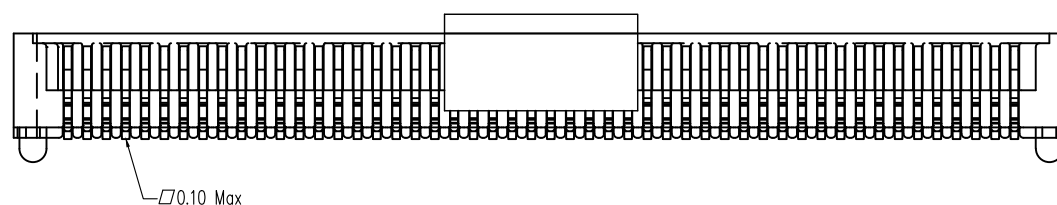
B.Plating: Gold plating

C.Temperature: -55° to 125°

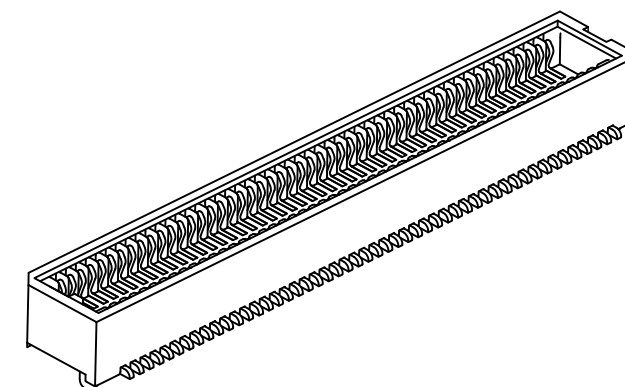
D.Electrical:

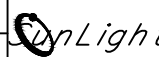
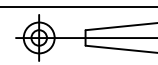
1. Voltage : 50V.
2. Current : 0.5A.
3. Contact Resistance : 40m Ω max.
4. Dielectric Withstanding Voltage : 500V AC / 1 min.
5. Insulation Resistance : 100M Ω min.

E.Available Pins : 20~100 Contacts



PCB Layout For
Surface Mounting



TOLERANCE .X ±0.30 .XX ±0.20 .XXX±0.10	DRAWER <i>Haw Feng Liu</i>	 日亮電子科技有限公司 Sun-Light Electronic Technologies Inc.	
	CHECK <i>Haw Feng Liu</i>		
	DESIGNED <i>Chin Chun Liu</i>	NAME 10+Gbps 0.50mm (0.0197") Pitch Board To Board Female connectors A-type H=2.74mm	
	APPROVAL <i>Haw Feng Liu</i>		
 UNITS : mm	DATE 7/17/2018	PART NO. ER05BTB-FAXXX	DRAW NO. ER05BTB-FA
	SCALE 5 : 1	SHEET 3 OF 3	REV. A